

Introduction to STM32 development board

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- 1、 Initial understanding of STM32F103ZET6
 - 1.1、 ST official study materials
 - 1.2、 Peripherals of STM32F103ZET6
- 2、 STM32F103ZET6 programming method
 - ST-LINK burning method

1、 Initial understanding of STM32F103ZET6

1.1、 ST official study materials

1. www.stmcu.org.cn :This website is a link to the ST Chinese community, which includes information on all MCUs of ST, such as: STM32F1 latest chip documentation (reference manual, data manual, errata manual, programming manual, etc.), software resources (firmware library, configuration tools, PC software, etc.), hardware resources (various official evaluation boards), etc.
2. https://www.st.com/content/st_com/zh.html :This URL is the official link of ST. You can get the latest and most complete information about ST on the website. For beginners, it is okay to obtain ST official information from the ST Chinese community. Because the information of the ST Chinese community is generally moved from ST's official website, but if you want to find the latest STM32 information, you still have to go to ST's official website to search.

1.2、 Peripherals of STM32F103ZET6

As you can see from the figure below, the peripherals supported by ZET6 include: 2 basic timers, 4 general timers, 2 advanced timers, 2 DMA controllers (total 12 channels), 3 SPI, 2 I2C, 5 serial ports, 1 USB, 1 CAN, 3 12-bit ADCs, 1 12-bit Dacs, 1 SDIO interface, 1 FSMC interface, and 112 general IO interfaces

Table 2. STM32F103xC, STM32F103xD and STM32F103xE features and peripheral counts

Peripherals		STM32F103Rx			STM32F103Vx			STM32F103Zx		
Flash memory in Kbytes		256	384	512	256	384	512	256	384	512
SRAM in Kbytes		48	64 ⁽¹⁾		48	64		48	64	
FSMC		No			Yes ⁽²⁾			Yes		
Timers	General-purpose	4								
	Advanced-control	2								
	Basic	2								
Comm	SPI(I ² S) ⁽³⁾	3(2)								
	I ² C	2								
	USART	5								
	USB	1								
	CAN	1								
	SDIO	1								
GPIOs		51			80			112		
12-bit ADC		3			3			3		
Number of channels		16			16			21		
12-bit DAC		2								
Number of channels		2								
CPU frequency		72 MHz								
Operating voltage		2.0 to 3.6 V								
Operating temperatures		Ambient temperatures: –40 to +85 °C /–40 to +105 °C (see Table 10) Junction temperature: –40 to + 125 °C (see Table 10)								
Package		LQFP64	WLCSP64		LQFP100, BGA100			LQFP144, BGA144		

1. 64 KB RAM for 256 KB Flash are available on devices delivered in CSP packages only.

2. For the LQFP100 and BGA100 packages, only FSMC Bank1 and Bank2 are available. Bank1 can only support a multiplexed NOR/PSRAM memory using the NE1 Chip Select. Bank2 can only support a 16- or 8-bit NAND Flash memory using the NCE2 Chip Select. The interrupt line cannot be used since Port G is not available in this package.

3. The SPI2 and SPI3 interfaces give the flexibility to work in an exclusive way in either the SPI mode or the I²S audio mode.

2. STM32F103ZET6 programming method

ST-LINK burning method

wiring

ST-link V2 debug downloader	STM32F103ZET6
VCC	3V3
SWDIO	SWDIO
SWCLK	SWCLK
GND	GND

Software used: STM32CubeIDE

For the specific construction of the development environment, please refer to the [Development Environment Construction and Use] content in the tutorial, so I won't go into details here.